

CALL FOR PAPERS



15h European Advanced Technology Workshop ON MICROPACKAGING AND THERMAL MANAGEMENT 5&6 FEBRUARY 2020 (WEDNESDAY & THURSDAY)

Conference Chair:

Jean-Yves SOULIER (ZODIAC AEROSPACE)

Technical Programme Committee:

Mohamad ABO RAS (BERLINER NANOTEST)

Jacques FAVRE (aPSI^{3D})

Thomas HARDER (ECPE)

Jean-Pierre FRADIN (ICAM)

Joel LALLIER, (THALES SYSTEMES AEROPORTES)

Sandrine LELONG-FENEYROU (ZODIAC AEROSPACE)

Bruno LEVRIER (BRUNO LEVRIER EXPERTISES)

Claude SARNO (THALES AVIONICS)

Dave SAUMS (DS & A LLC)

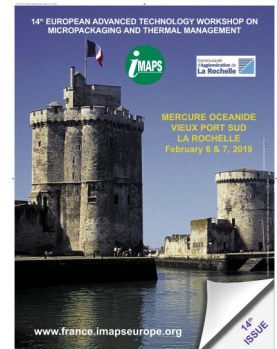
Raphael SOMMET (LABORATOIRE XLIM

UNIVERSITE DE LIMOGES)

We are pleased to open the Call for Papers of the 14th Advanced Technology Workshop on Micropackaging and Thermal Management which will be held in La Rochelle in February 2019. This yearly conference has grown year after year by the number of presented papers and attendees. Be part of a successful 2019 edition and be sure to submit your abstract on time.

The workshop sessions will include the following topics. Papers are invited in following areas:

- Cooling solutions for microelectronics packaging,
- Micro-cooling solutions,
- Heat conductive materials at chip, board, sub-system and system levels,
- Advances in PCBs for thermal management
- Thermal modeling and simulation,
- Heatsinks, heatpipes and other cooling products,
- Liquid and phase change cooling,
- New cooling solutions,
- Overviews or examples of products, systems cooling, power electronics, automotive transport, ...
- Thermal management of optoelectronics components (LEDs, IR sensors...),
- Reliability of electronic components over extended temperature range and under temperature variation..
- Thermal management aspects of 3D integration: thermal interface materials, dissipation from PCB embedded components and hot spots, and special techniques (e.g. micro-channels)

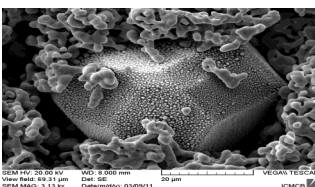


Speakers will submit a 200-300 words abstract detailing their presentation (20 minutes + 5 minutes for questions), no later than **11 October 2019**

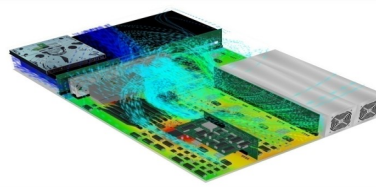
Speakers pay a reduced registration fee (520 € excluding VAT including hotel accommodation for 2 nights and meals) and are also requested to attend the entire workshop to maximize opportunities of exchanging with other attendees.

Notification of acceptance by the Technical Committee: **15 November 2019** After notification of acceptance, you commit to attend the workshop or delegate someone else.

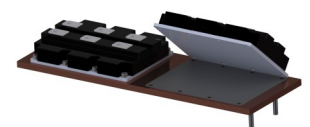
TABLE TOP EXHIBITION (limited number, first come first served basis): 1 table, 2 chairs 1 panel. Presentation of your activity, your latest products and results (only for companies in relation to thermal management), 320 € excluding VAT.



Courtesy of ICMCB & Novapack



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